

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6639383

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JHON JHY LIAW	02/19/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17222143
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ATTORNEY DOCKET NUMBER:	2013-1726/24061.2730US06
NAME OF SUBMITTER:	LINDA INGRAM
SIGNATURE:	/Linda Ingram/
DATE SIGNED:	04/05/2021
Total Attachments: 2	
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source=2730US06_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I,

(1) Jhon Jhy Liaw of No. 15, Lane 447, Xuefu E. Road
Zhudong Township, Hsinchu County 310
Taiwan R.O.C.

have invented certain improvements in

STRUCTURE AND METHOD FOR FINFET SRAM

for which I have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and

X filed on February 27, 2014, and assigned application number 14/191,789; and

WHEREAS, I authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the

Docket No.: 2013-1726/24061.2730

Customer No.: 42717

said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jhon Jhy Liaw

Residence Address: No. 15, Lane 447, Xuefu E. Road, Zhudong Township
Hsinchu County 310, Taiwan R.O.C.

Dated: Feb. 19, 2004

Jhon Jhy Liaw
Inventor Signature
